COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE

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<th>BOARD #: 001</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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PLOT NAME = Top Assembly Drawing

| GENERATED | 10/29/2015 12:14:45 PM | TEXAS INSTRUMENTS |
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

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